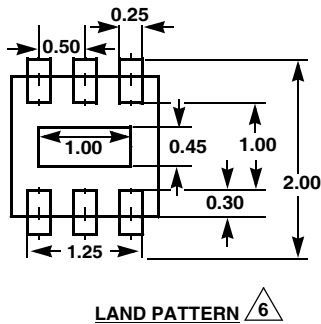
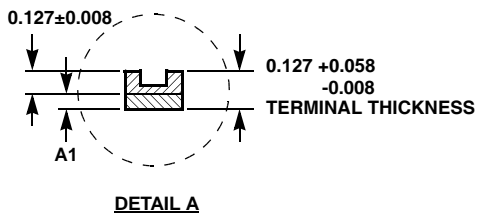
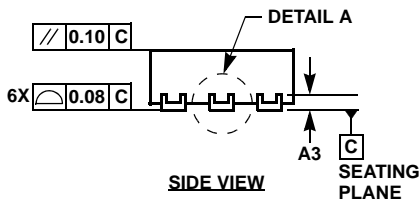
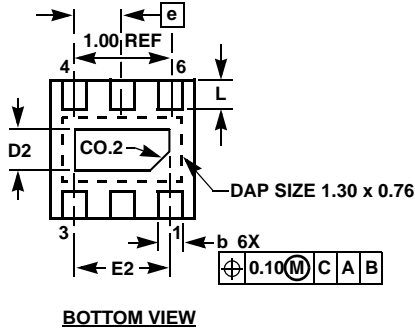
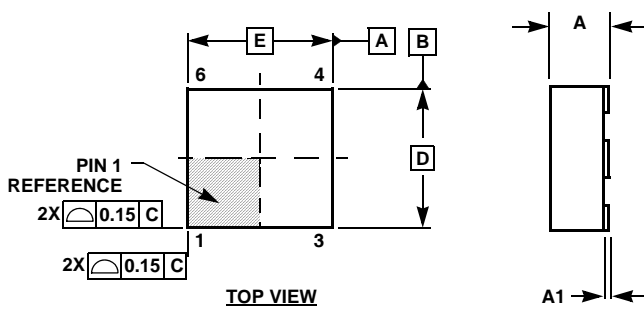


Ultra Thin Dual Flat No-Lead Plastic Package (UTDFN)



L6.1.6x1.6A

6 LEAD ULTRA THIN DUAL FLAT NO-LEAD PLASTIC PACKAGE

SYMBOL	MILLIMETERS			NOTES
	MIN	NOMINAL	MAX	
A	0.45	0.50	0.55	-
A1	-	-	0.05	-
A3	0.127 REF			-
b	0.15	0.20	0.25	-
D	1.55	1.60	1.65	4
D2	0.40	0.45	0.50	-
E	1.55	1.60	1.65	4
E2	0.95	1.00	1.05	-
e	0.50 BSC			-
L	0.25	0.30	0.35	-

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NOTES:

1. Dimensions are in mm. Angles in degrees.
2. Coplanarity applies to the exposed pad as well as the terminals. Coplanarity shall not exceed 0.08mm.
3. Warp page shall not exceed 0.10mm.
4. Package length/package width are considered as special characteristics.
5. JEDEC Reference MO-229.
6. For additional information, to assist with the PCB Land Pattern Design effort, see Intersil Technical Brief TB389.